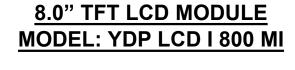
PRODUCT SPECIFICATION





- < >> Preliminary Specification
- < >> Finally Specification

	CUSTOMER'S APPROVAL				
CUSTOMER:					
SIG	NATURE:	DATE:			

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
-	TFT S. G. H 20240515	TFT 周福云 20240515	TFT L. L 20240515

knitter-switch

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2024.05.15	LL	Initial Release	

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs, and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	8.0"	
LCD type	IPS TFT	
Display Mode	Transmissive /Normally Black	
Resolution	800 RGB x 1280	Pixels
View Direction	Full Viewing	Best Image
Module Outline	114.54(H) x184.04 (V) x 2.53(T) (Note1)	mm
Active Area	(107.64)(H) x(172.224)(V)	mm
Pixel Size	134.55(H)x134.55(V)	um
Pixel Arrangement	R.G.B. Stripe	
Display Colors	16.7M	
Driver IC	JD9365DA-H3	
Interface	MIPI	
With or Without TP	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	TBD	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

ltem	Symbol	Min.	Max.	Unit
	VDD	-0.3	3.6	V
Power voltage	AVDD	-0.3	6.6	V
	AVEE	0	-6.6	V
Storage temperature	Tstg	-30	+80	°C
Operating temperature	Тор	-20	+70	°C

Vss=0V, Ta=25°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit
	VDD	2.8	3.3	3.6	V
Power voltage	AVDD	4.5	-	6.3	V
	AVEE	-4.5	-	-6.3	V
Input logic high voltage	V _{IH}	0.7*VDD	-	VDD	V
Input logic low voltage	V _{IL}	0	-	0.3*VDD	V
Output logic high voltage	V _{OH}	0.8*VDD	-	VDD	V
Output logic low voltage	V _{OL}	0	-	0.2*VDD	V
Current Consumption All white	ldd	-	TBD	-	mA

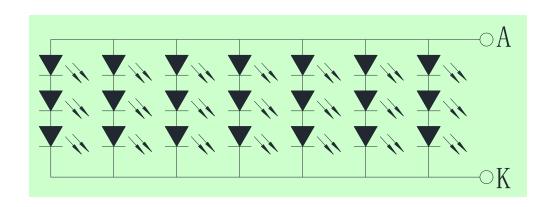
5. Backlight Characteristic

5.1. Backlight Characteristic

Item	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	VF	Ta=25 °C, I _F =20mA/LED	8.4	9.0	10.2	٧
Forward Current	lF	Ta=25 °C, VF=3.0V/LED	-	140	-	mA
Power dissipation	Pd		-	1260	-	W
Uniformity	Avg		-	80	-	%
LED working life(25°C)	-	30000 - he				
Drive method	Constant current					
LED Configuration	21 V	Vhite LEDs(3 LEDs in one s	string and	d 7 group	s in para	llel)

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness. The environmental conducted under ambient air flow, at Ta= 25 ± 2 °C,60%RH ±5 %, I_F=20mA/LED.

5.2. Backlighting circuit



6. Optical Characteristics

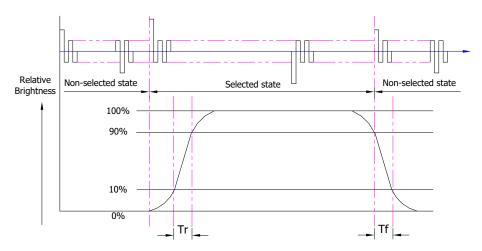
6.1. Optical Characteristics

Ta=25°C, VDD=3.3V

	Item		Symbol	Condition	S	pecification	on	Unit
	item		Symbol	Condition	Min.	Тур.	Max.	Unit
	Luminance on							
	TFT(I_f =20mA/LED		Lv	Normally viewing angle	280	350	-	cd/m²
Mode)	Contrast ratio(See 6.3)	(See 6.3)	CR		1200	1500	-	
E	Response	time	Tr	$\begin{array}{c} T_{R} \\ \hline T_{F} \end{array}$		30	35	ma
Si K	(See 6	.2)	TF		-	30	35	ms
l iš		Red	XR		-	TBD	-	
nsr	(See 6 Chromaticity Transmissive (See 6.5)	Red	YR		-	TBD	-	
Ta		Green	XG		-	TBD	-	
	Chromaticity Transmissive	, l	Yg		-	TBD	-	
5	(See 6.5)	Blue	Хв		-	TBD	-	
<u>ig</u>	(366 0.3)	blue	Yв		-	TBD	-	
K		White	Xw		-	TBD	•	
<u> </u>		vvriite	Yw		-	TBD	-	
	Viewing	Horizont	θх+		-	80	-	
	Viewing	al	θх-	Center CR≥10	-	80	-	Deg
	Angle (See 6.4)	Vertical	φY+	Center CR210	-	80	-	Deg.
	(See 6.4)	vertical	φY-		-	80	-	
	NTSC Ratio	(Gamut)			-	60	-	%

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

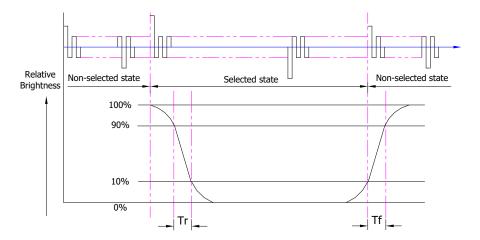


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

6.3. Definition of Contrast Ratio

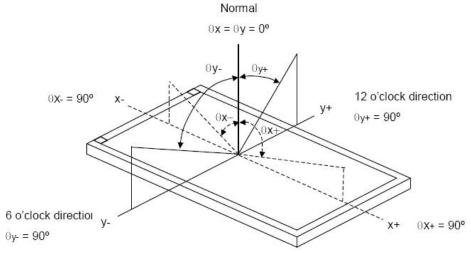
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent		
Measuring Point Diameter	3mm//1mm		
Measuring Point Location	Active Area centre point		
Toot nottorn	A: All Pixels white		
Test pattern	B: All Pixel black		
Contrast setting	Maximum		

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles

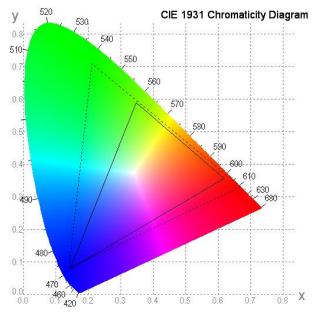


Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance: L_V = average (L_{P1} : L_{P9})
- 6.6.2. Uniformity = Minimal (L_{P1} : L_{P9}) / Maximal (L_{P1} : L_{P9}) * 100%
- 6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

X X/6 X/3 X/3 X/6 X/3 X/6 Display Area

Y/6

Y/3

Y/3

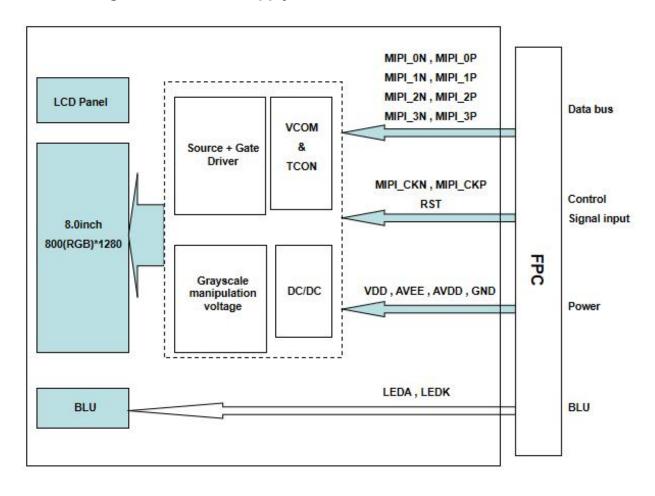
7

8

9

Note: Measuring machine: BM-7

7. Block Diagram and Power Supply



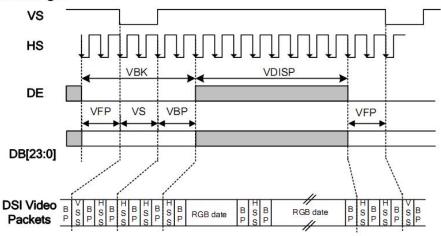
8. Interface Pins Definition

No.	Symbol	Function	Remark
1	GND	Ground	
2	VDD	Power supply	
3	VDD	Power supply	
4	GND	Ground	
5	RST	Global reset pin	
6	NC	No connection	
7	NC	No connection	
8	AVEE	Analog supply negative voltage	
9	AVDD	Analog supply positive voltage	
10	GND	Ground	
11	MIPI_0N	MIPI Negative data signal (-)	
12	MIPI_0P	MIPI Positive data signal (+)	
13	GND	Ground	
14	MIPI_1N	MIPI Negative data signal (-)	
15	MIPI_1P	MIPI Positive data signal (+)	
16	GND	Ground	
17	MIPI_CKN	MIPI Negative clock signal (-)	
18	MIPI_CKP	MIPI Positive clock signal (+)	
19	GND	Ground	
20	MIPI_2N	MIPI Negative data signal (-)	
21	MIPI_2P	MIPI Positive data signal (+)	
22	GND	Ground	
23	MIPI_3N	MIPI Negative data signal (-)	
24	MIPI_3P	MIPI Positive data signal (+)	
25	GND	Ground	
26	NC	No connection	
27	LEDA	LED Anode	
28	LEDA	LED Anode	
29	LEDK	LED cathode	
30	LEDK	LED cathode	

9. Timing Characteristics

1) Timings for DSI video mode

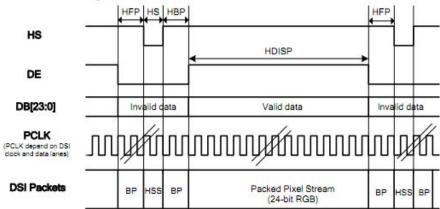
Vertical Timings



Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Vertical low pulse width	VS		2	4	200 Note(1)	Line
Vertical front porch	VFP	-	4	20	200	Line
Vertical back porch	VBP		2	10	200 Note(1)	Line
Vertical blanking period	VBK	VS+VBP+VFP	8	34	250	Line
Vertical active area	4	VDISP	(()	1280	-	Line
Vertical Refresh rate	VRR	<u> </u>	(2)	60	-	Hz

Note: (1) The VS and VBP pulse width are related to GIP start pulse and GIP clock pulse timing. The GIP start pulse and GIP clock pulse must be set at corresponding position for LCD normal display.

Horizontal Timings

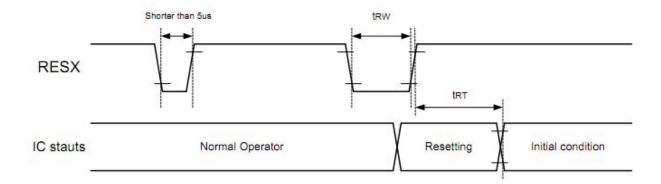


Item	Symbol	Condition	Min.	Тур.	Max.	Unit
HS low pulse width	HS	-	6	18	-	DCK
Horizontal back porch	HBP	-	5	18		DCK
Horizontal front porch	HFP		5	18		DCK
Horizontal blanking period	HBLK	HS+HBP+HFP	16	54 (Note1)	-	DCK
Horizontal active area	HDISP	- 4	-	800		DCK
Pixel Clock	PCLK		63.06 (Note2)	67.33 (Note2)		MHz

Note 1: HS+HBP > 0.5us.

Note 2: Pixel Clock = (HBLK+HDISP) * (VBK+VDISP) * Frame rate, Frame rate=60Hz.

2) Reset input timings



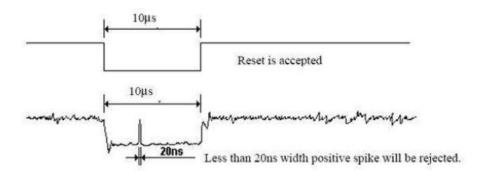
Symbol	Parameter	Related pins	Min.	Max.	Unit
t _{RW}	Reset pulse width ⁽²⁾	RESX	10	-	μs
t _{RT}	Deset complete time (3)	000	2	5 (Note 5)	ms
	Reset complete time ⁽³⁾		-	120 (Note 6, 7)	ms

Note: (1) The reset complete time also required time for loading ID bytes from OTP to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

(2) Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 5 µs	Reset Rejected
Longer than 10 µs	Reset
Between 5 µs and 10 µs	Reset Start

- (3) During the resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode) and then returns to Default condition for H/W reset.
- (4) Spike Rejection also applies during a valid reset pulse as shown below:



- (5) When Reset is applied during Sleep In Mode.
- (6) When Reset is applied during Sleep Out Mode.
- (7) It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.
- (8) After Sleep Out Command, it is necessary to wait 120msec then send RESX.

10. Quality Assurance

10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, normal inspection.

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5
Electrical functional: AQL 0.65

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3. Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
 - 10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
 - 10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
 - 10.3.1.3. If can not finish the analysis on time, customer will be notified with the progress status.
- 10.3.2. Disposition of nonconforming:
 - 10.3.2.1. Non-conforming product over PPM level will be replaced.
 - 10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

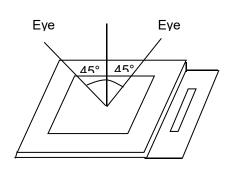
10.4.Agreement Items

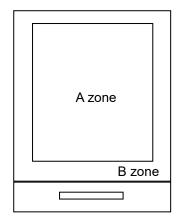
Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

10.5. Standard of the Product Visual Inspection

- 10.5.1. Appearance inspection:
 - 10.5.1.1. The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm.
 - 10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
 - 10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,





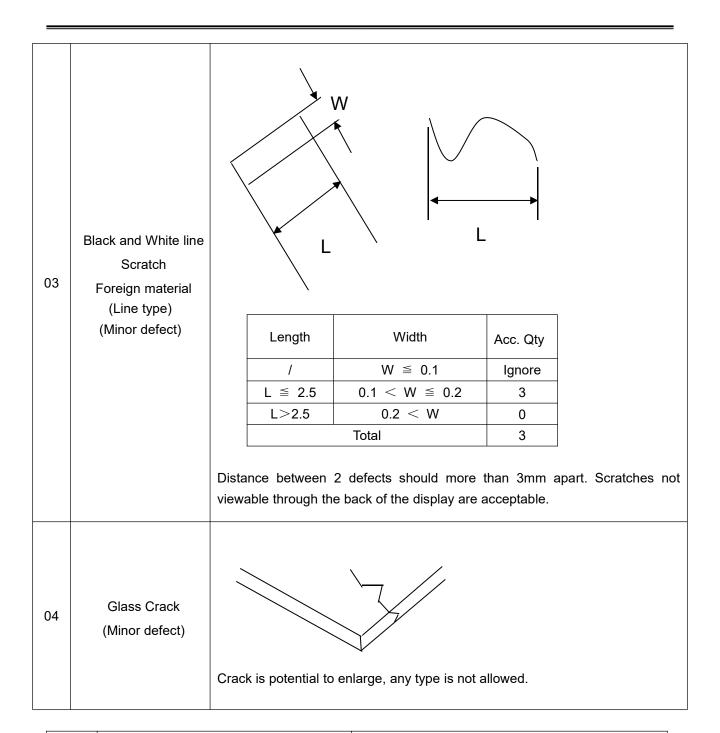
10.5.2. Basic principle:

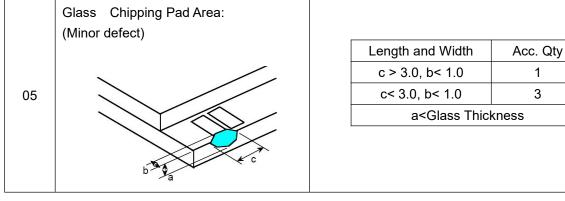
10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

10.5.2.2. New item must be added on time when it is necessary.

10.6.Inspection Specification for the TFT module

No.	Item	Criteria (Unit: mm)			
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	b φ= (a + b) /2 Distance between 2 defects she	0.20<	Area ≤0.20 <φ≤0.50 50<φ	Acc. Qty Ignore N≤3 0
02	Electrical Defect	Bright dot Dark dot Total dot	splay Area N≤2 N≤4 N≤4	Total N≤2 N≤4 N≤4	Note1
02	(Minor defect)	Mura Not visible through 5% ND filters.		Note2	
		Remark: 1. Bright dot caused by scratch	and foreign ob	ject accords to	item 1.





	Glass Chipping Rear of Pad Area: (Minor defect)					
		Length and Width	Acc. Qty			
		c > 3.0, b< 1.0	1			
06		c< 3.0, b< 1.0	2			
		c< 3.0, b< 0.5	4			
		a <glass td="" thick<=""><td>ness</td></glass>	ness			
	b a c					
	Glass Chipping Except Pad Area: (Minor defect)					
		Length and Width	Acc. Qty			
		c > 3.0, b< 1.0	1			
07		c< 3.0, b< 1.0	2			
		c< 3.0, b< 0.5	4			
	0 3	a <glass td="" thick<=""><td>ness</td></glass>	ness			
	a					
	Glass Corner Chipping: (Minor defect)					
	(Willion derest)	Length and Width	Acc. Qty			
		c < 3.0, b< 3.0	Ignore			
08		a <glass td="" thickness<=""></glass>				
	ba					
	Glass Burr:					
	(Minor defect)	Length	Acc. Qty			
		F < 1.0	Ignore			
09	F	Glass burr don't affect ass dimension.	semble and module			
	F C C C C C C C C C C C C C C C C C C C					

10	FPC Defect: (Minor defect)		10.1 Dent, pinhole (w: circuitry width.) 10.2 Open circuit is 10.3 No oxidation,	
11	Bubble on Polarizer (Minor defect)		Diameter φ≤0.30 0.30 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤2 N=0
12	Dent on Polarizer (Minor defect)		Diameter φ≤0.25 0.25 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤4 None
13	Bezel	•	tortion on the Bezel. Ingerprints, stains or oth	er contamination.
14	РСВ		t layout.	CB terminals. me as documented on the
15	Soldering	Follow IPC-A-61	0C standard	
16	Electrical Defect (Major defect)	16.1 Missing ver 16.2 Abnormal D 16.3 No function	or no display. seeds product specificati g angle defect. nt. ght.	

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

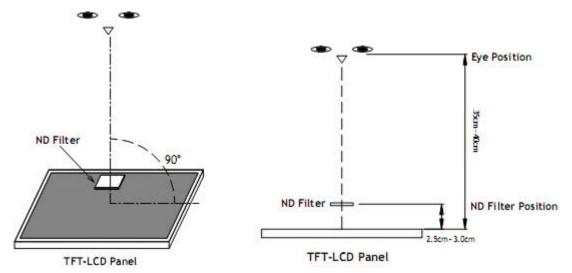
10.8.Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9. Packaging

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: \pm 4KV 150pF/330 Ω 5 times	2	GB/T17626.2
	Liectrical Static Discharge	Contact: \pm 2KV 150pF/330 Ω 5 times	2	-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.7 -2018

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1.Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2. Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting

Solder Pin Lead

Recommended

Solder Pin Lead

Not Recommended

12.4.2. Pins of EL

12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

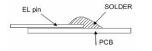
Typical Soldering Time: ≤2s

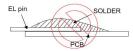
Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting





Recommended

Not Recommended

12.4.2.7. The type of the solder iron:





Recommended

Not Recommended

12.4.2.8. Solder Pad



12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

12.6. Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7. Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

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14. Outline Drawing

